

A1
wherein said first back-illuminated semiconductor image pickup element and said second semiconductor image pickup element are secured such that respective fronts of said first back-illuminated semiconductor image pick-up element and said second semiconductor image pickup element are closer to each other than their respective backs.

A2
3. (Amended) A semiconductor device comprising:
a first back-illuminated semiconductor image pickup element; and
a second semiconductor image pickup element made of a semiconductor material different from that of said first back-illuminated semiconductor image pickup element,
wherein said first back-illuminated semiconductor image pickup element is disposed such that respective photosensitive regions of said first back-illuminated semiconductor image pickup element and said second semiconductor image pickup element are adjacent to each other,
and
wherein mutually opposite faces of said first back-illuminated semiconductor image pickup element and said second semiconductor image pickup element are adhered via at least three or more bumps.

Please add new claim 10 as follows:

A3
10. The semiconductor device as recited in claim 1, wherein mutually opposite faces of said first back-illuminated semiconductor image pickup element and said second semiconductor image pickup element are adhered via at least three or more bumps.
